WHAT CLAIMED IS:

1. An electrode substrate of a plasma display panel, having an electrode pattern on a glass substrate, and being made by baking and removing a resin binder component of a conductive pattern composed of a conductive ink,

wherein the conductive pattern composed of the conductive ink is formed by printing the conductive inkn on the glass substrate by an intaglio offset printing method;

wherein the conductive ink is formed by dispersing or dissolving a metal powder and a resin binder into a solvent; and

wherein a printing blanket used for printing the conductive pattern has a rubber layer on a surface of the printing blanket, and the rubber layer poses a volume increasing rate under 20% when the rubber is immersed in the solvent of the conductive ink for 24 hours at 23°C.

2. The electrode substrate of claim 1, wherein the rubber layer is composed of a silicon rubber with a hardness (JIS A) of 20~80° and a ten-point mean roughness (Rz) of 0.01~3.0μm.

3. The electrode substrate of claim 2, wherein the rubber layer is composed of the silicon rubber with a hardness (JIS A) of 20~70° and a ten-point mean roughness (Rz) of less than 1μm.

4. A method for manufacturing an electrode substrate of a plasma display panel, comprising steps of:

filling a conductive ink into cavities of an intaglio, wherein the conductive ink is formed by dispersing or dissolving a metal powder and a resin binder into a solvent;

transferring the conductive ink from the cavities of the intaglio onto a printing blanket, wherein the printing blanket has a rubber layer as a surface layer of the printing

blanket, and the rubber layer poses a volume increasing rate under 20% when the rubber is immersed in the solvent of the conductive ink for 24 hours at 23°C;

transcribing the conductive ink from the surface layer of the printing blanket onto a glass substrate; and

baking a conductive pattern composed of the conductive ink composition formed on the surface of the glass substrate to remove a resin binder component of the conductive pattern

5. The method of claim 4, wherein the rubber layer is composed of a silicon rubber with a hardness (JIS A) of 20~80° and a ten-point mean roughness (Rz) of 0.01~3.0μm.

6. The method substrate of claim 5, wherein the rubber layer is composed of the silicon rubber with a hardness (JIS A) of 20~70° and a ten-point mean roughness (Rz) of less than 1μm.

7. A method for manufacturing an electrode substrate of a plasma display panel, comprising steps of:

filling a conductive ink into cavities of an intaglio, wherein the conductive ink is formed by dispersing or dissolving a metal powder and a resin binder into a solvent;

performing following processes (i) and (ii) in a sequence;

(i) transferring the conductive ink from the cavities of the intaglio to a surface of a printing blanket;

(ii) transferring the conductive ink from the surface of the printing blanket to a surface of a glass substrate; and

baking a conductive pattern composed of the conductive ink formed on the surface of the glass substrate to remove a resin binder component of the conductive pattern;

wherein after the processes (i) and (ii) are performed in the sequence for one, two

or more times, the printing blanket is heated such that a surface temperature T_B of the printing blanket is about 40~200°C, and then the printing blanket is cooled in a condition that the surface temperature T_B (°C) of the printing blanket with respect to a surface temperature T_P (°C) of the intaglio satisfies a following equation

$$| T_P - T_B | \leq 5°C.$$

8. The method of claim 7, wherein the rubber layer is composed of a silicon rubber with a hardness (JIS A) of 20~80°, a ten-point mean roughness (Rz) of 0.01~3.0μm, and a thickness of 1~1500μm.